



ORIENTAL
SEMICONDUCTOR

GreenMOS™

OSG60R260xF_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

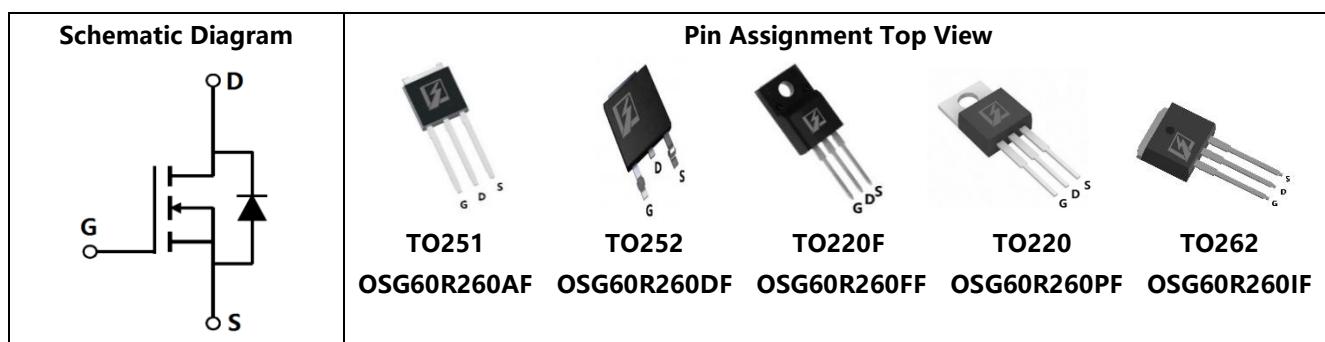
- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger

■ General Description

OSG60R260xF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

◆ V_{DS} , min@ T_{jmax}	650 V
◆ I_D , pulse	45 A
◆ $R_{DS(ON)}$, max @ $V_{GS}=10$ V	260 mΩ
◆ Q_g	17.8 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	600	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	15	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		9.3	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	45	A
Power dissipation ³⁾ for TO251, TO252, TO220 , $T_C=25^\circ\text{C}$	P_D	104	W
Power dissipation ³⁾ for TO220F , $T_C=25^\circ\text{C}$		32	
Single pulsed avalanche energy ⁵⁾	E_{AS}	400	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...480$ V	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...480$ V, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO251/TO252/TO220/TO262	TO220F	
Thermal resistance, junction-case	R _{θJC}	1.2	3.9	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	600			V	V _{GS} =0 V, I _D =250 μA
		650	750			V _{GS} =0 V, I _D =250 μA T _j =150 °C
Gate threshold voltage	V _{GS(th)}	2.0		4.0	V	V _{DS} =V _{GS} , I _D =250 μA
Drain-source on-state resistance	R _{DS(ON)}		0.23	0.26	Ω	V _{GS} =10 V, I _D =7.5 A
			0.56			V _{GS} =10 V, I _D =7.5 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =600 V, V _{GS} =0 V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		1016		pf	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz
Output capacitance	C _{oss}		76.4		pf	
Reverse transfer capacitance	C _{rss}		3.36		pf	
Turn-on delay time	t _{d(on)}		31.3		ns	V _{GS} =10 V, V _{DS} =480 V, R _G =25 Ω, I _D =15 A
Rise time	t _r		40.8		ns	
Turn-off delay time	t _{d(off)}		43.7		ns	
Fall time	t _f		47.3		ns	

■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		17.8		nC	$I_D=15\text{ A}$, $V_{DS}=480\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		5.1		nC	
Gate-drain charge	Q_{gd}		6.3		nC	
Gate plateau voltage	$V_{plateau}$		5.6		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			15	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			45		
Diode forward voltage	V_{SD}			1.4	V	$I_S=15\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		313.1		ns	$V_R=400\text{ V}, I_S=15\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		3.6		μC	
Peak reverse recovery current	I_{rrm}		21.7		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=150\text{ V}$, $R_G=25\text{ }\Omega$, $L=10.8\text{ mH}$, starting $T_j=25\text{ }^{\circ}\text{C}$.

■ Electrical Characteristics Diagrams

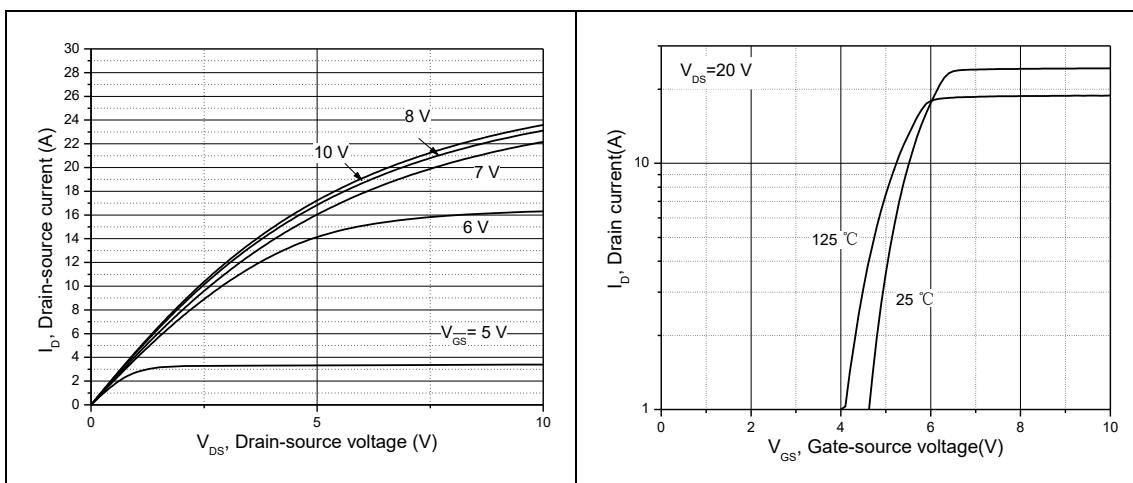


Figure 1, Typ. output characteristics

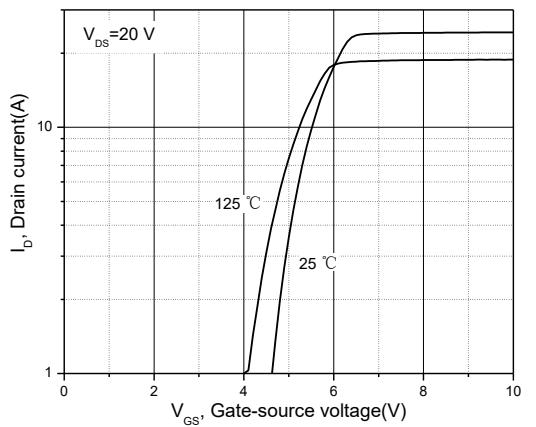


Figure 2, Typ. transfer characteristics

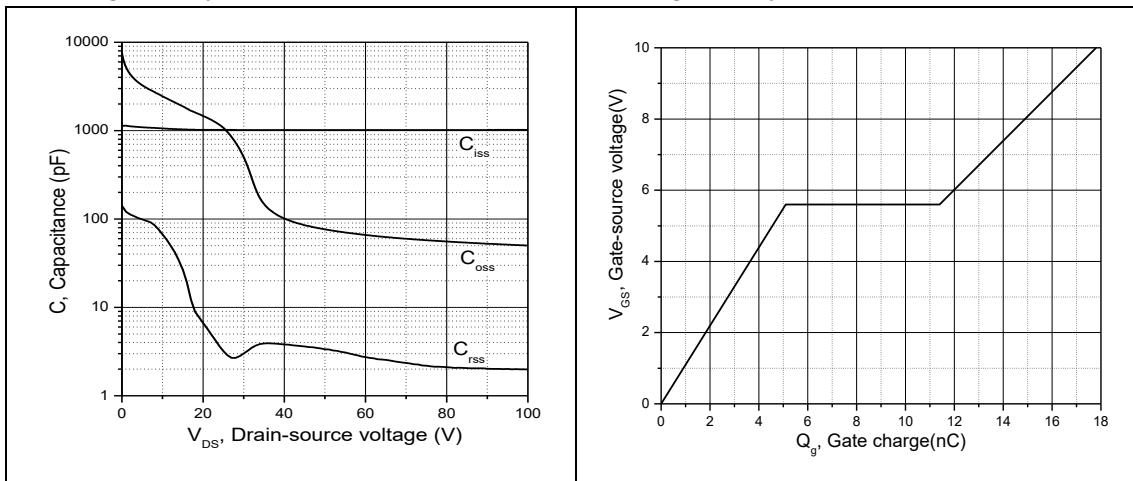


Figure 3, Typ. capacitances

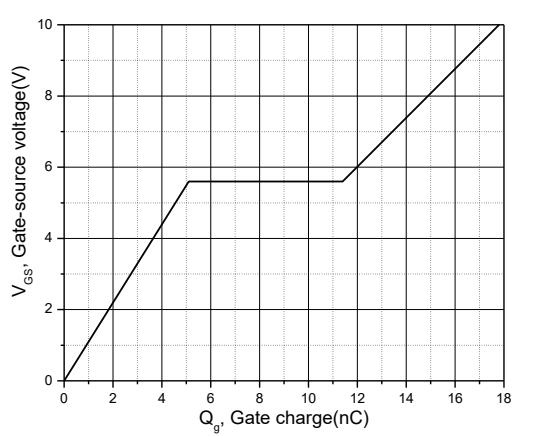


Figure 4, Typ. gate charge

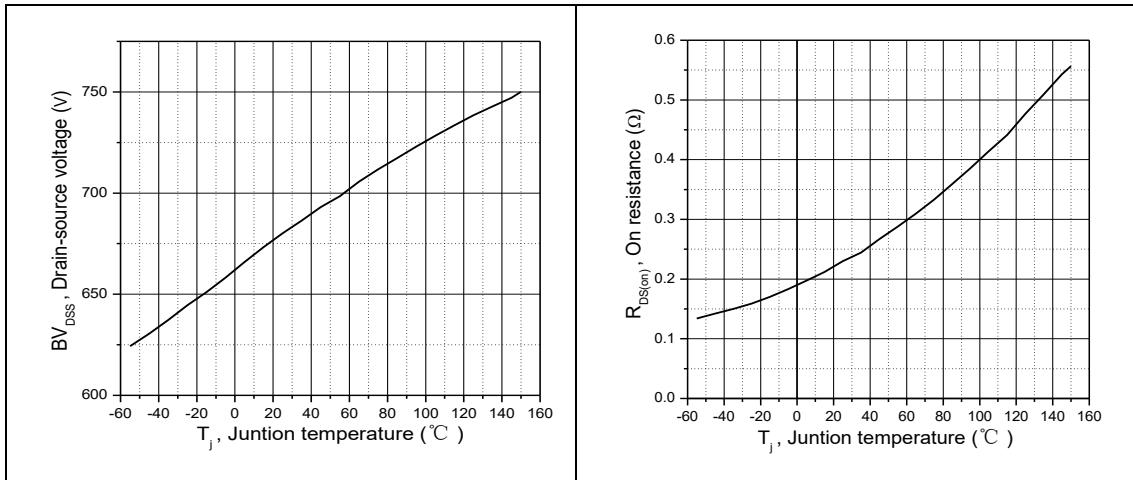


Figure 5, Drain-source breakdown voltage

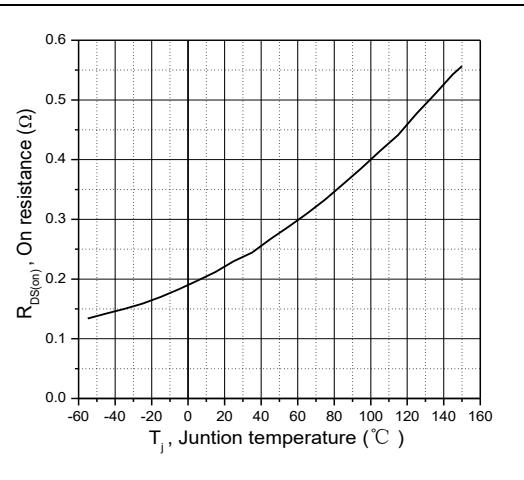


Figure 6, Drain-source on-state resistance

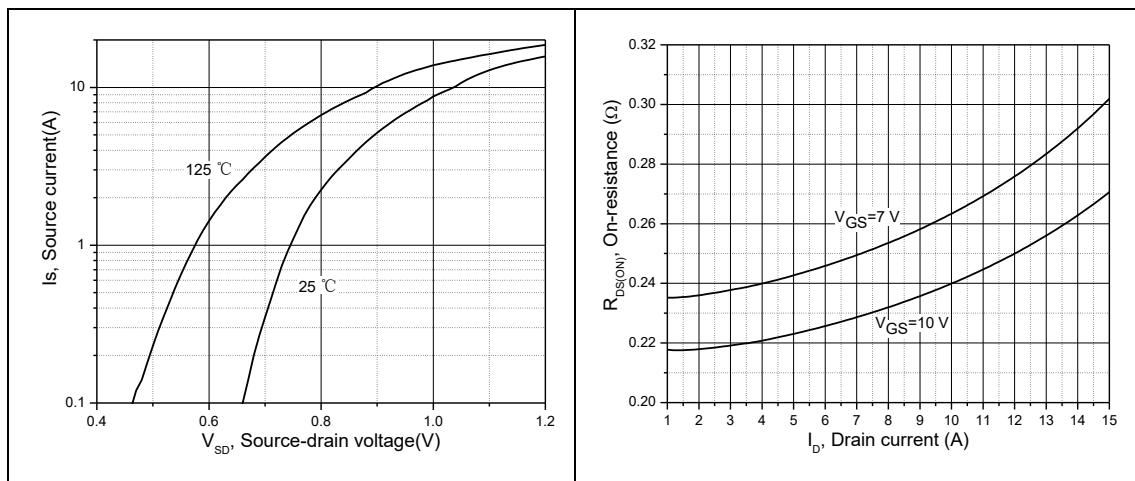


Figure 7, Forward characteristic of body diode

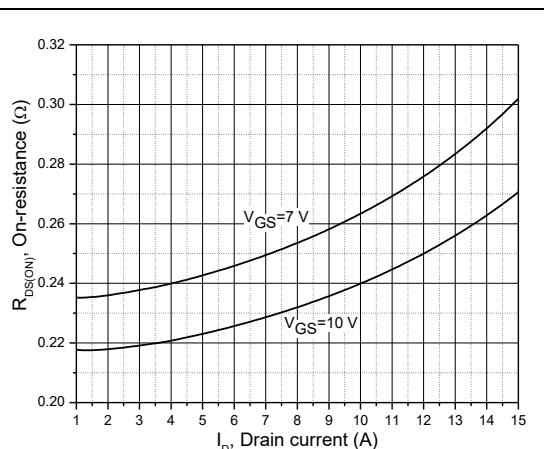


Figure 8, Drain-source on-state resistance

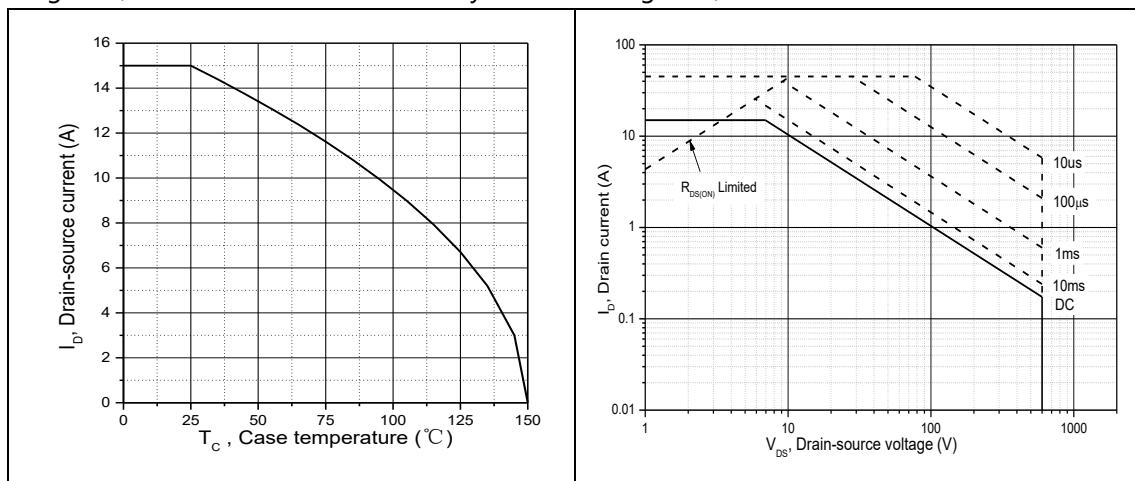
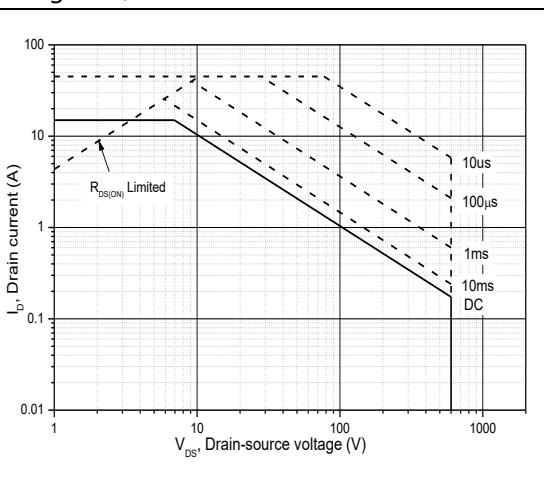
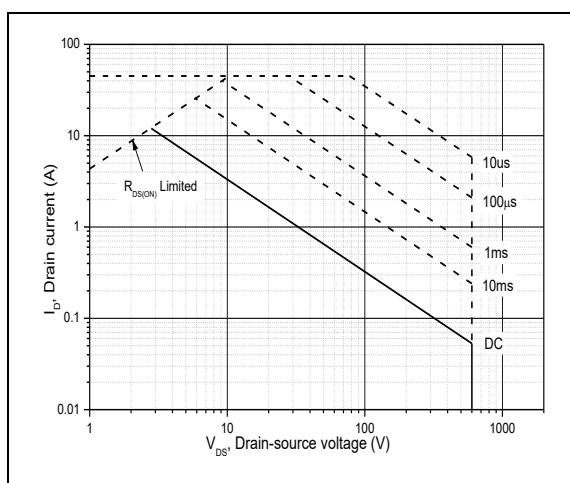


Figure 9, Drain current


 Figure 10, Safe operation area for
 TO251/TO252/TO220/TO262 $T_C=25\text{ }^{\circ}\text{C}$

 Figure 11, Safe operation area for TO220F
 $T_C=25\text{ }^{\circ}\text{C}$

■ Test circuits and waveforms

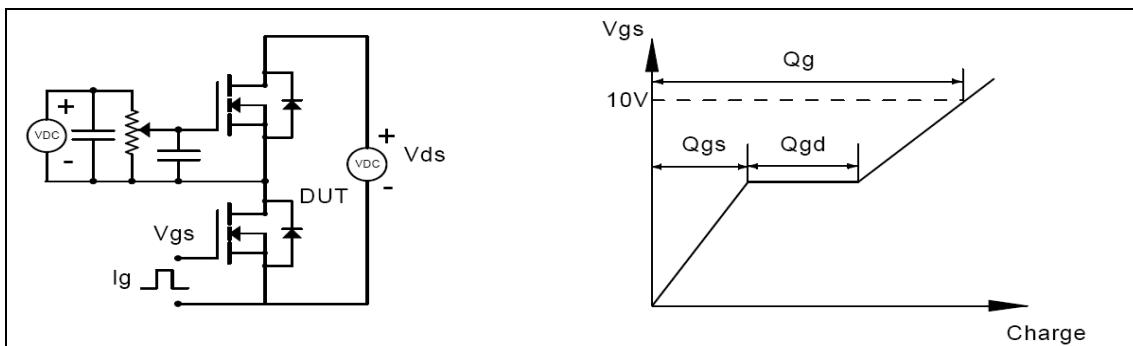


Figure 1, Gate charge test circuit & waveform

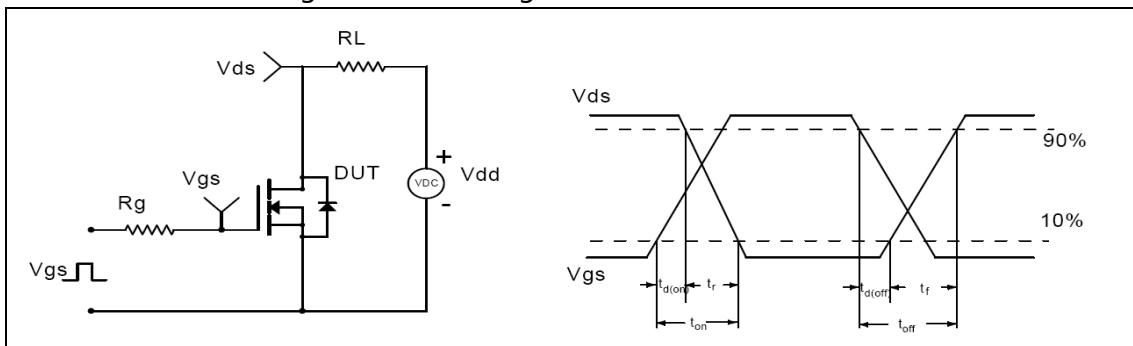


Figure 2, Switching time test circuit & waveforms

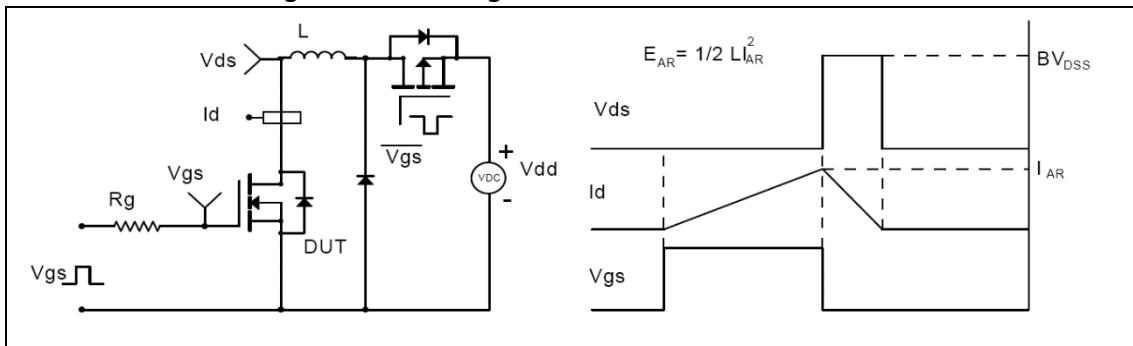


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

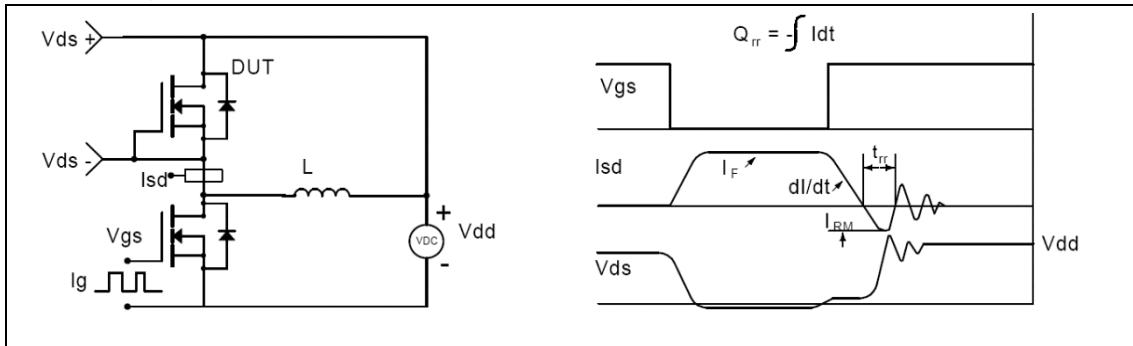
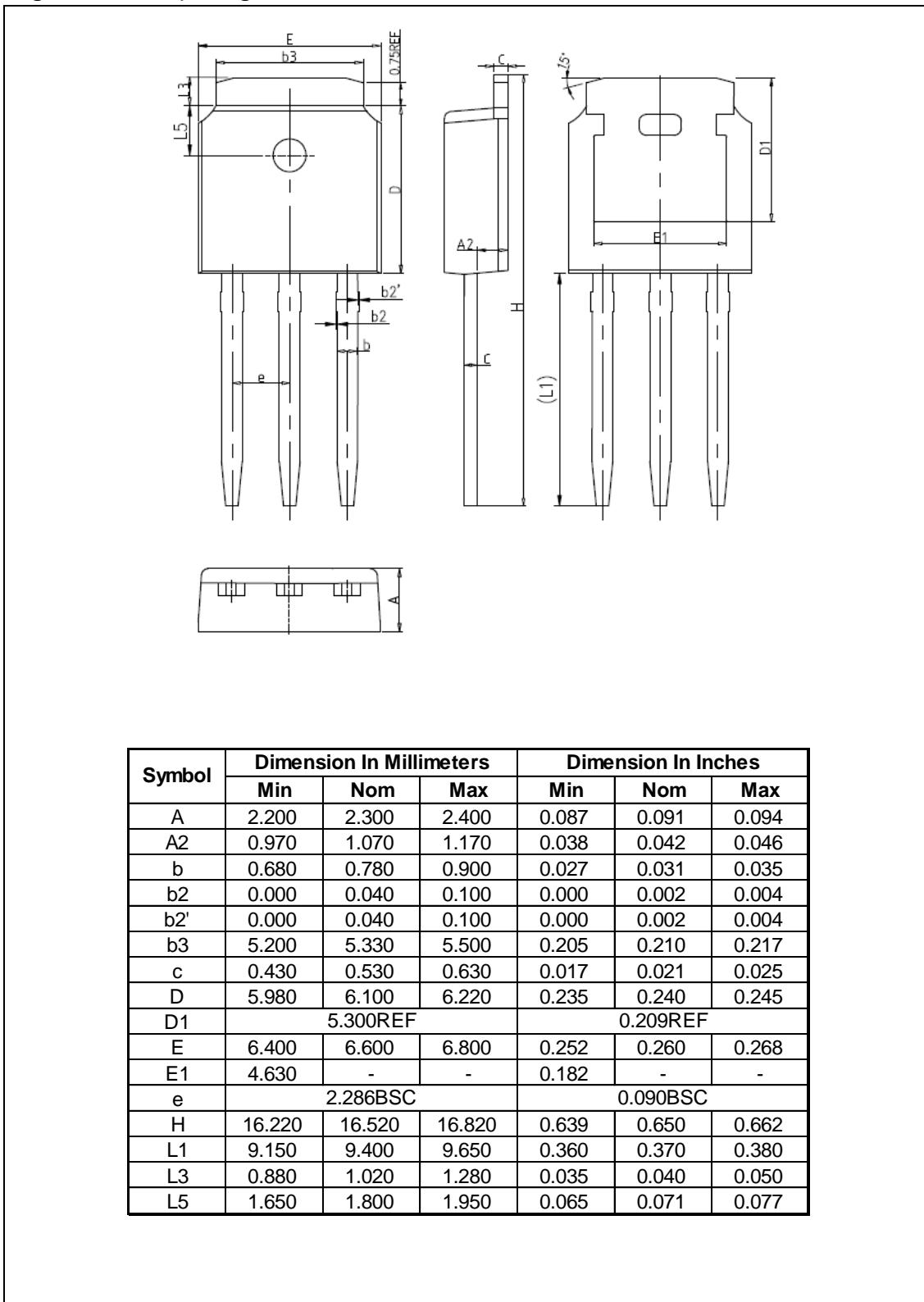


Figure 4, Diode reverse recovery test circuit & waveforms

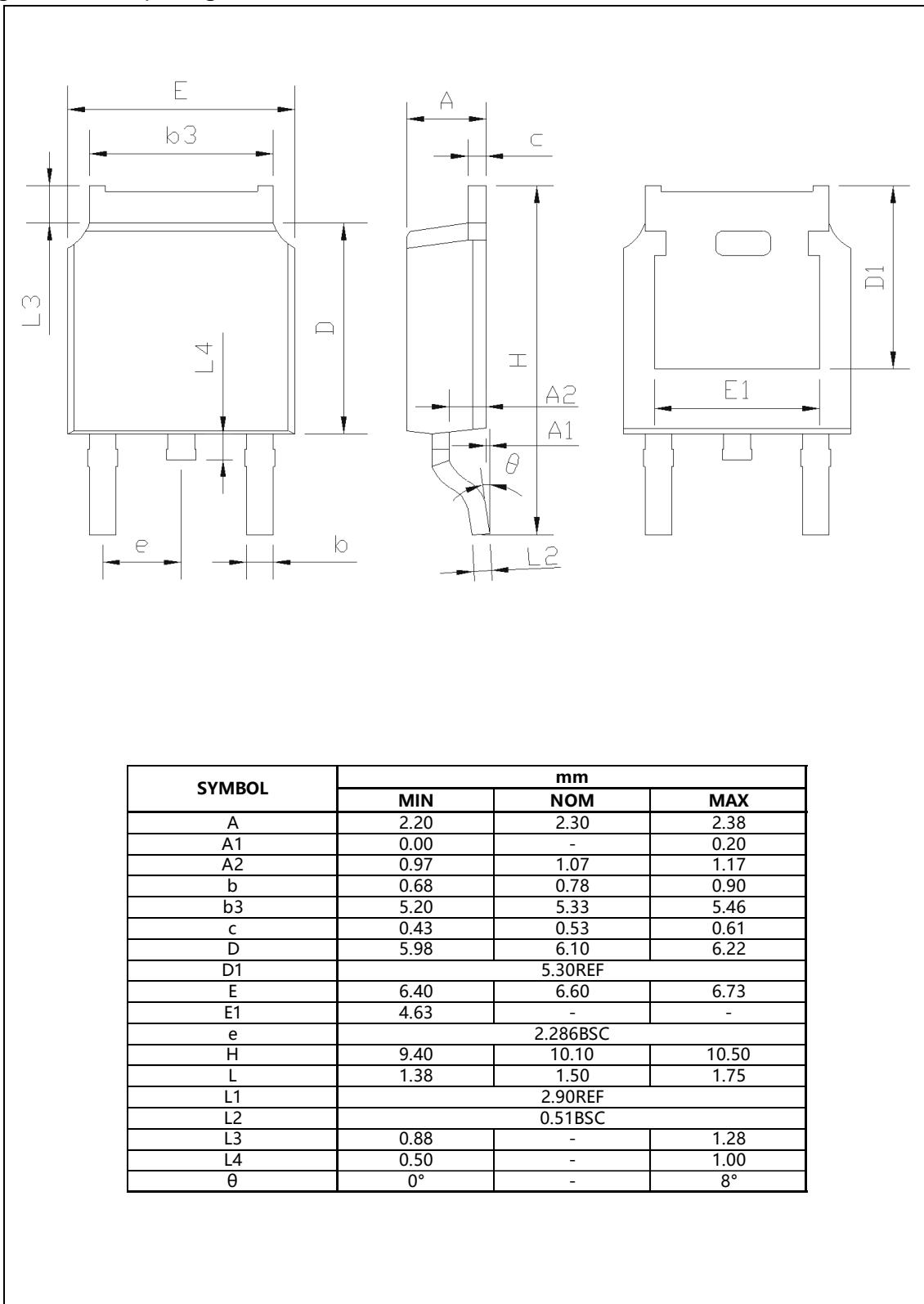
■ Package Information

Figure1, TO251 package outline dimension



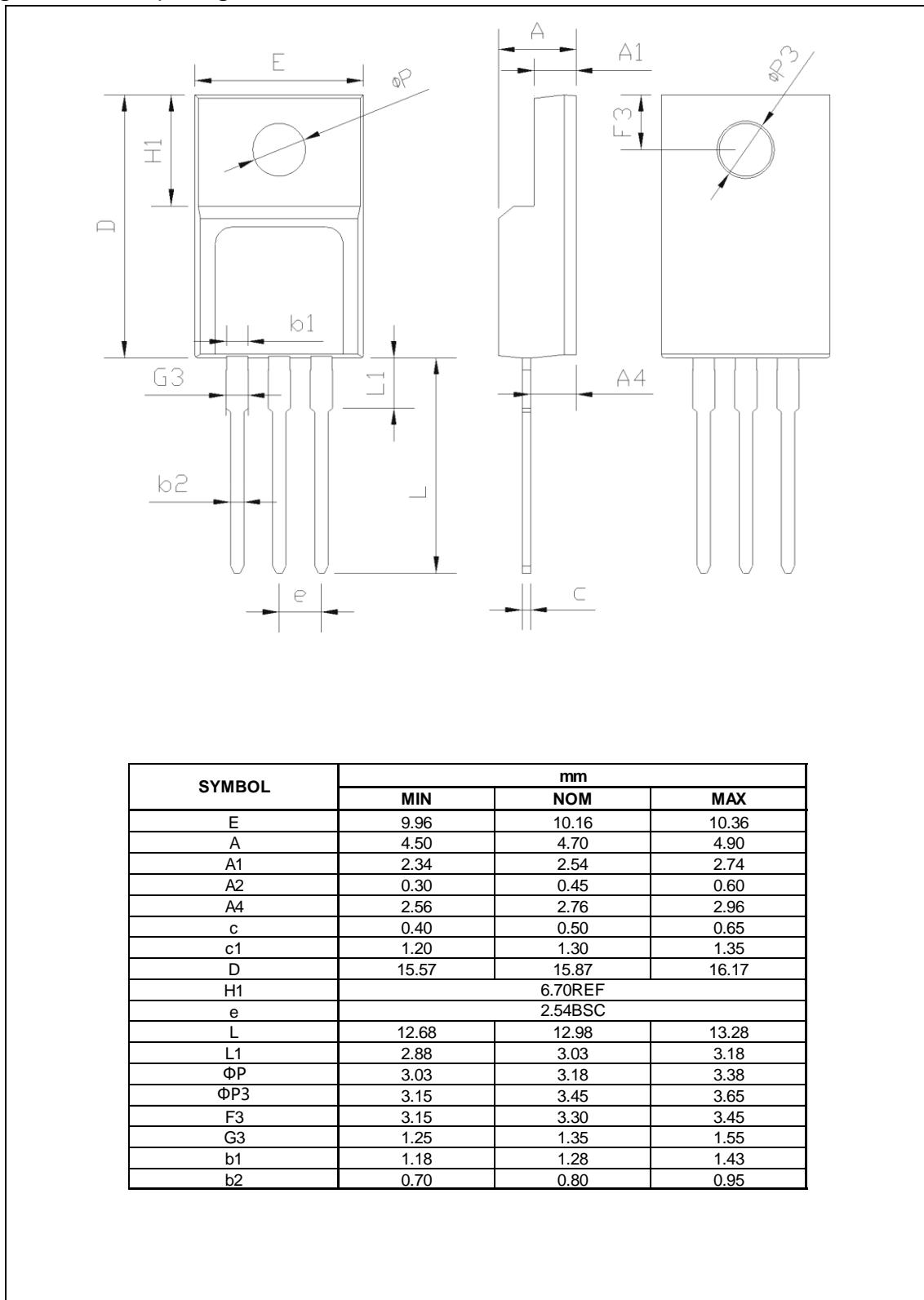
■ Package Information

Figure2, TO252 package outline dimension



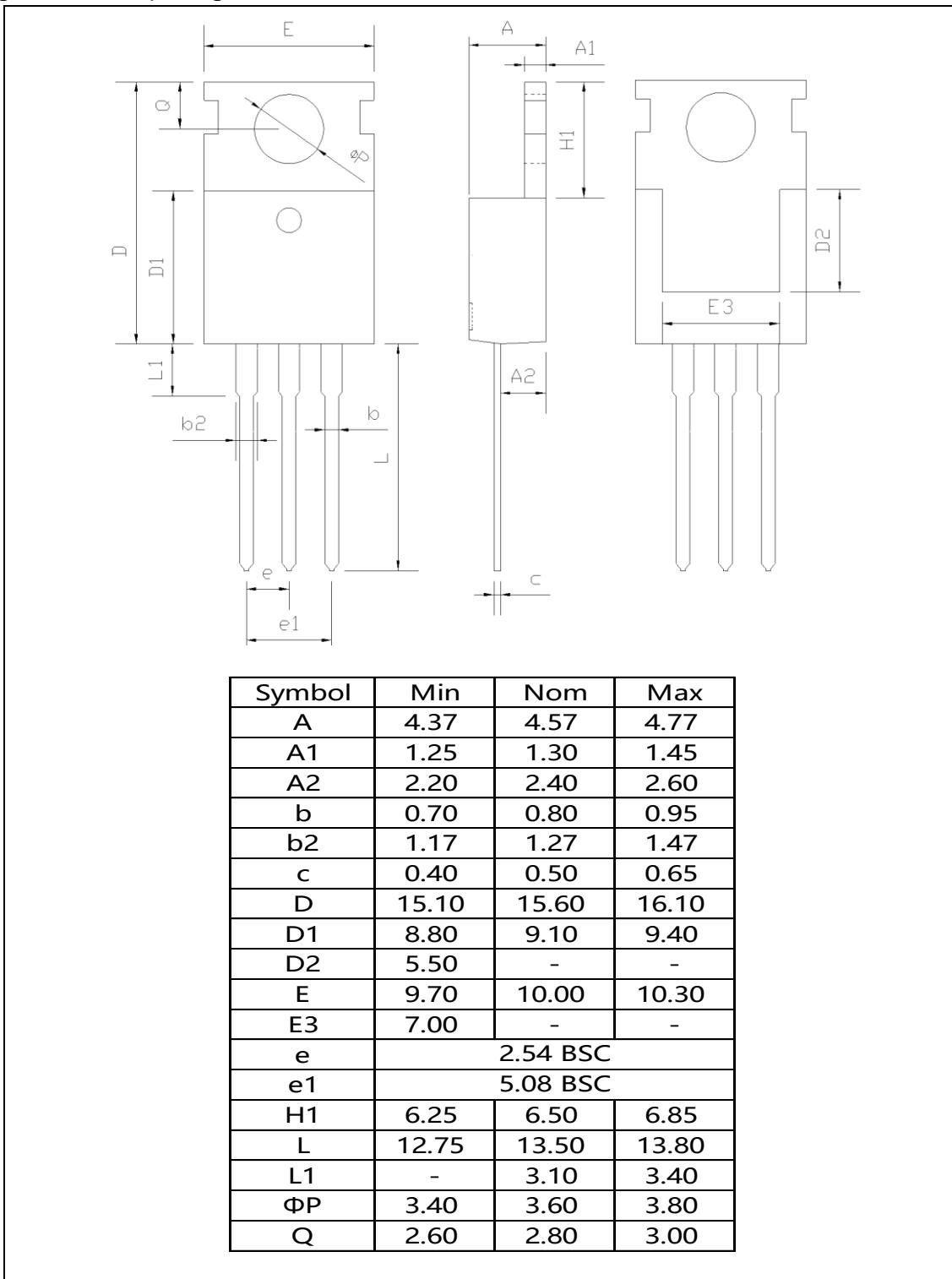
■ Package Information

Figure3, TO220F package outline dimension



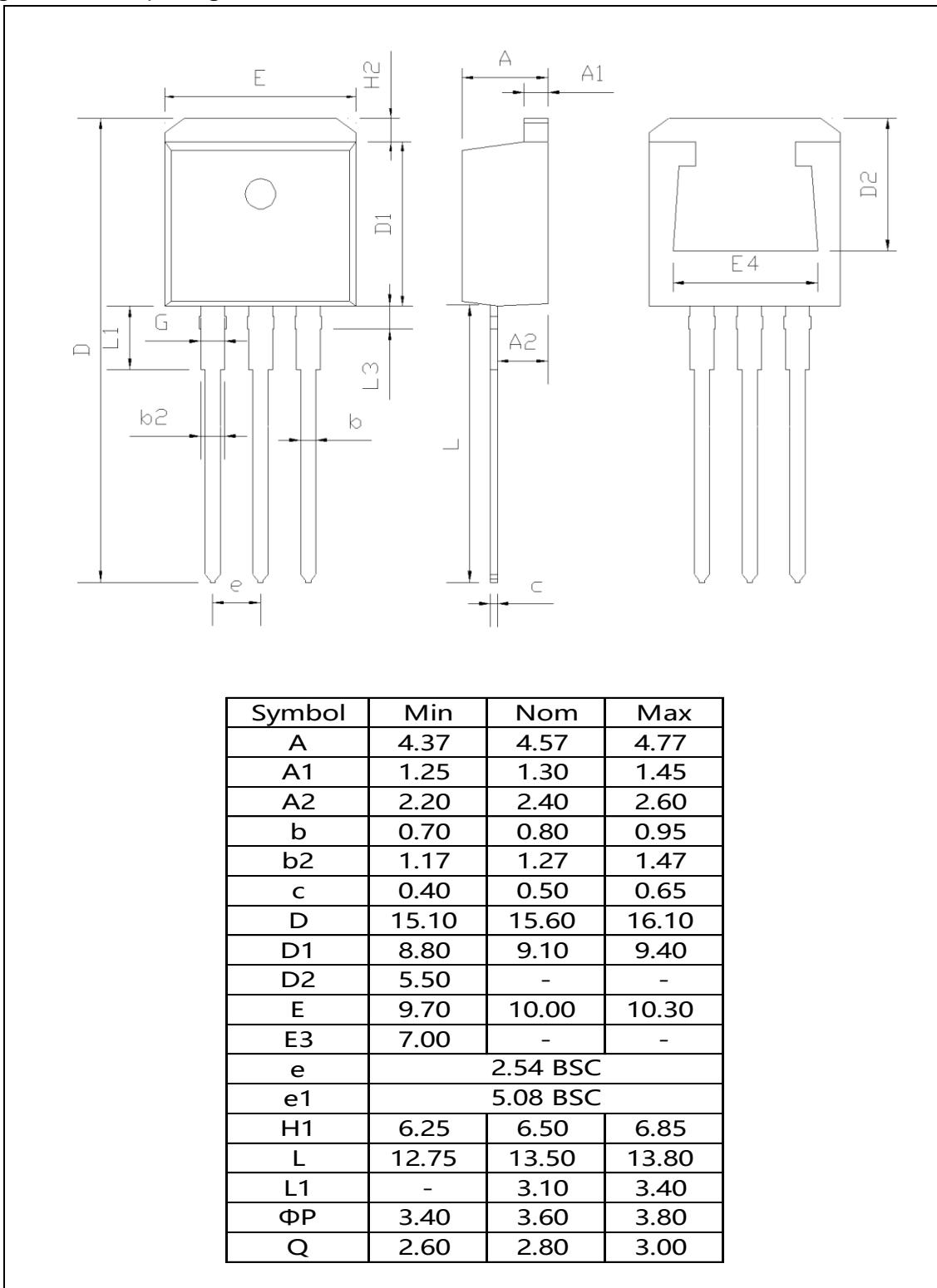
■ Package Information

Figure4, TO220 package outline dimension



■ Package Information

Figure5, TO262 package outline dimension



■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO251	75	66	4950	6	29700
TO262	50	20	1000	6	6000
TO220	50	20	1000	6	6000
TO220F	50	20	1000	6	6000

Package	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO252	2500	2	5000	5	25000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R260AF	TO251	yes	yes	yes
OSG60R260DF	TO252	yes	yes	yes
OSG60R260FF	TO220F	yes	yes	yes
OSG60R260PF	TO220	yes	yes	yes
OSG60R260IF	TO262	yes	yes	yes